



SUA-110H24-30xx-S277

鍍層厚度:	COLOR:
Blank : 1u"	BLUE : Blank
2 : 15u"	Black : B
3 : 30u"	Red : R

NOTE:

1.MATERIAL:

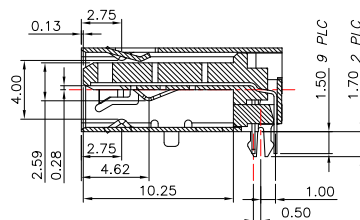
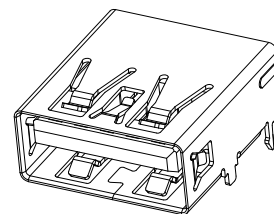
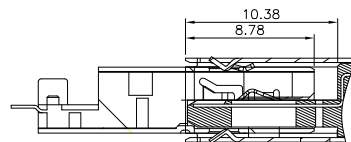
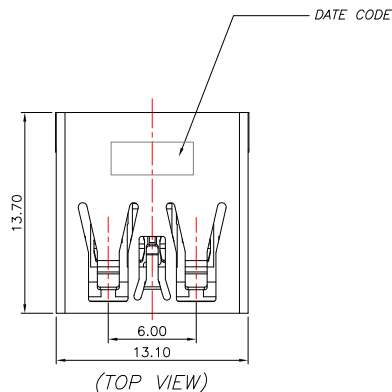
- 1.1 Housing: LCP,(UL94V-0)
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

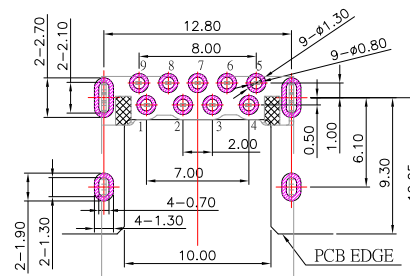
- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

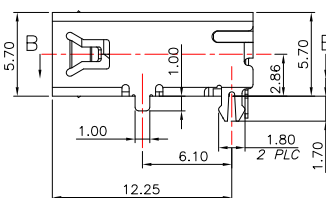
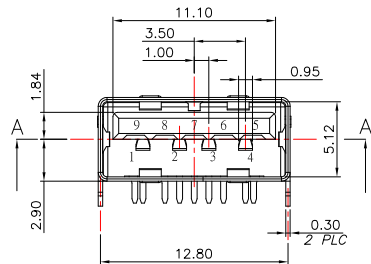
- 3.1 Current Rate: 1.5 A
- 3.2 insulator Resistance: 100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -40°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



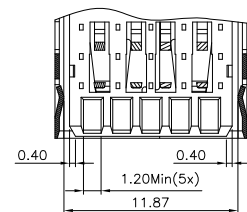
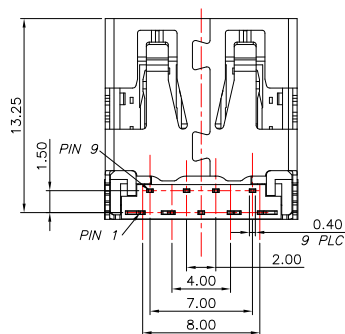
SECTION B-B



RECOMMENDED PCB LAYOUT (TOP VIEW)



SECTION A-A



Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST

ITEM NO.	DESCRIPTION	DRAWN	DATE
5	更新pcb layout	Jack	030520
4	新增pcb layout尺寸	Jack	101619
3	更新pcb layout	Jack	092618
2	更新為A0版	Jack	051617
1	更新尺寸6.6改6.1	Jack	040715

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/05/20			
CHECKED BY:	DATE	FINISH	MODLE	USB A/F DIP R/A TYPE
Jacky Chen	03/05/20			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110H24-30xx-S277
Tony Kao	03/05/20	1 : 1	PART NO.	SUA-110H24-30xx-S277
		SHEET NO.	1 of 1	
			SIZE	A4
			VER	R5